Scintera®

Recommended Reflow Profile for Pb-Free Solder Paste (9mm x 9mm QFN)

Profile Specification	Pb-Free Assembly
Temperature minimum (T_{smin})	150°C
Temperature maximum (T_{smax})	200°C
Time (Tsmin to Tsmax) (t_s)	60–120 seconds
Average ramp-up rate (T_{smax} to T_p)	3°C/second maximum
Liquidous temperature (T_L)	217°C
Time at liquidous (t_L)	60–150 seconds
Peak package body temperature (T_c)	260°C
Time (t_p) within 5°C of the peak package body temperature (T_C)	30 seconds maximum
Average ramp-down rate (T_p to T_{smax})	6°C/second maximum
Time 25°C to Peak	8 minutes maximum

Table 1: Reflow Profile

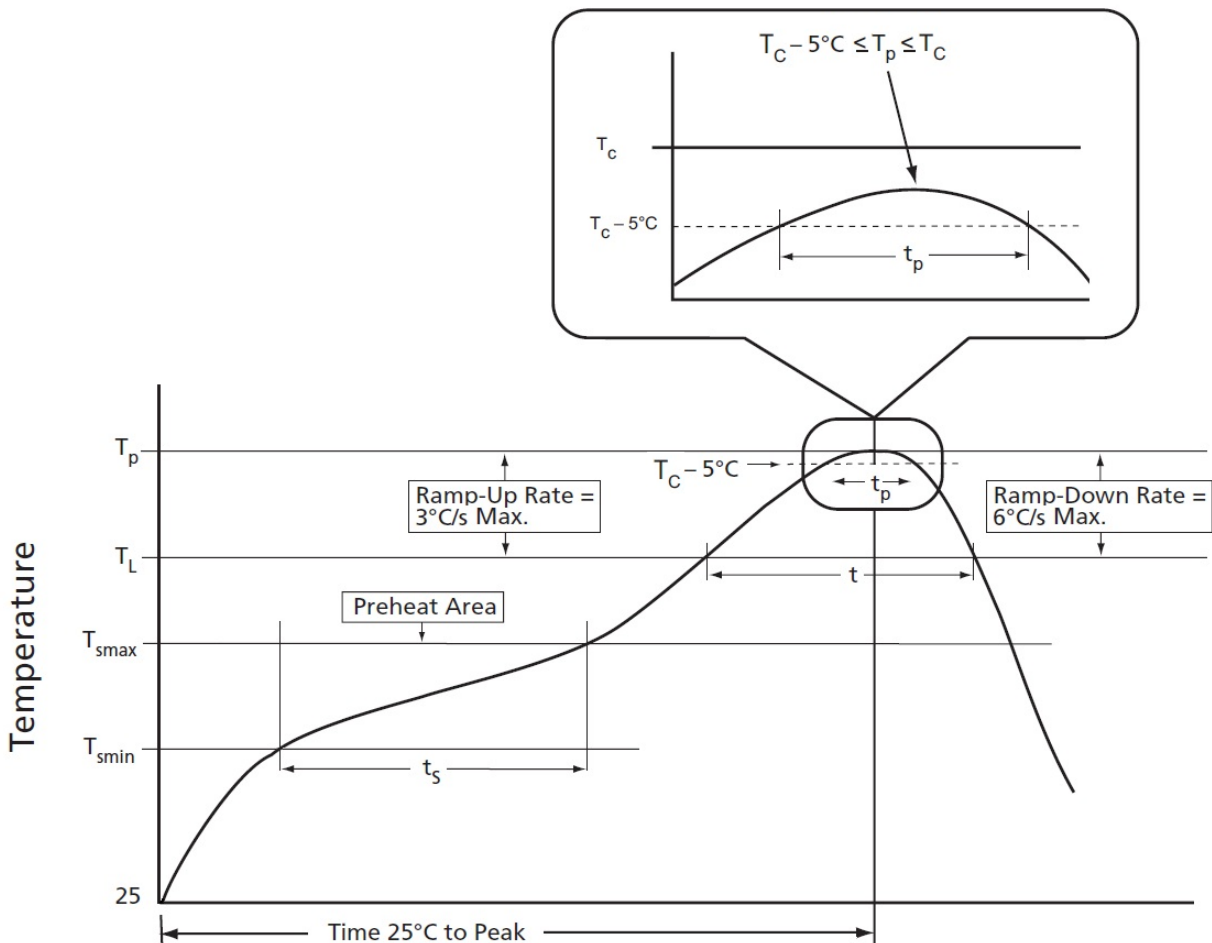

Figure 1: Reflow Diagram

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Note:

1) All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

2) Reflow profiles in this document are recommendations only and are not meant to specify board assembly profiles. Actual board assembly profiles should be developed based on specific process needs and board designs and should not exceed the parameters in Table 1.

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